## imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

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Transistors with Built-in Resistor DRC5614T0L

### DRC5614T0L Silicon NPN epitaxial planar type

For digital circuits / Muting DRC2614T in SMini3 type package

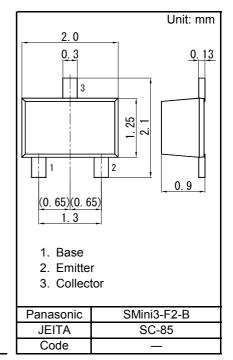
### Features

- Low collector-emitter saturation voltage Vce(sat)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

Absolute Maximum Ratings Ta = 25 °C

- Marking Symbol: VT
- Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



Symbol	Rating	Unit
VCBO	30	V
VCEO	20	V
VEBO	5	V
IC	600	mA
PT	150	mW
Tj	150	°C
Topr	-40 to +85	°C
Tstg	-55 to +150	°C
	VCBO VCEO VEBO IC PT Tj Topr	VCBO         30           VCEO         20           VEBO         5           IC         600           PT         150           Tj         150           Topr         -40 to +85

# Internal Connection $B \circ \stackrel{R_1}{\frown} \circ C$ $O \cap E$ Resistance value R1 10

## Panasonic

### Transistors with Built-in Resistor **DRC5614T0L**

V

V

V

μA

μA

\_

kΩ

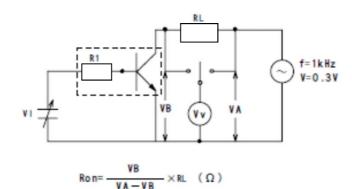
Ω

### Electrical Characteristics Ta = 25 °C ± 3 °C Parameter Symbol Conditions Min Typ Max Unit Collector-base voltage (Emitter open) VCBO IC = 10 µA, IE = 0 30 VCEO 20 Collector-emitter voltage (Base open) IC = 1 mA, IB = 0 Emitter-base voltage (Collector open) VEBO IE = 10 µA, IC = 0 5 Collector-base cutoff current (Emitter open) ICBO VCB = 30 V, IE = 0 1 Emitter-base cutoff current (Collector open) IEBO VEB = 5 V, IC = 0 1 VCE = 5 V, IC = 50 mA 100 600 Forward current transfer ratio \*1 hFE IC = 50 mA, IB = 2.5 mA Collector-emitter saturation voltage VCE(sat) 80 mV Input resistance R1 -30% 10 +30% On resistanc \*2 Ron 2.5 VI = 7 V, $RL = 1 k\Omega$ , f = 1 kHz

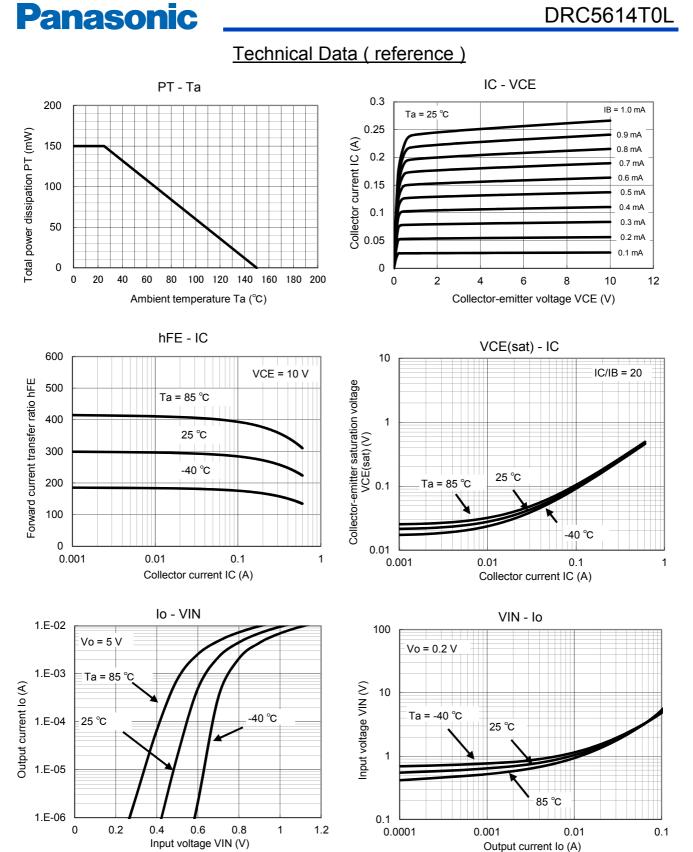
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. \*1 Pulse Test

\*2 On resistance test circuit



Transistors with Built-in Resistor **DRC5614T0L** 

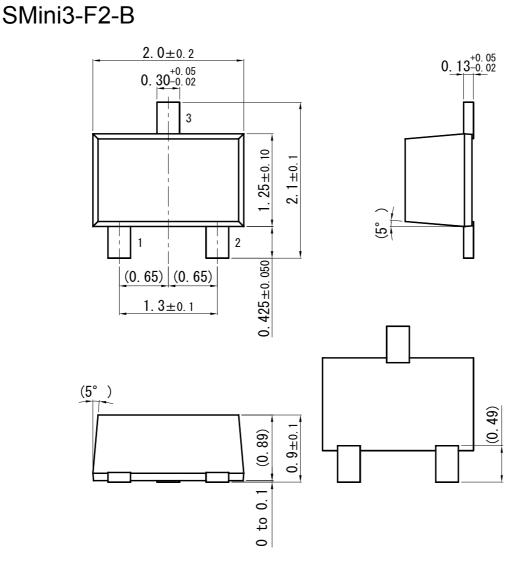


Established : 2010-04-22 : 2014-03-20 Revised

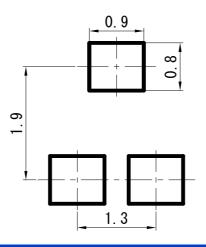


Transistors with Built-in Resistor DRC5614T0L

Unit: mm



Land Pattern (Reference) (Unit: mm)



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